

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kwan-soo Kim</td> <td>12/03/2012</td> </tr> <tr> <td>Tae-jong Lee</td> <td>12/03/2012</td> </tr> <tr> <td>Kang-sup Shin</td> <td>12/03/2012</td> </tr> <tr> <td>Si-bum Kim</td> <td>12/03/2012</td> </tr> <tr> <td>Yang-beom Kang</td> <td>12/03/2012</td> </tr> <tr> <td>Jong-yeul Jeong</td> <td>12/03/2012</td> </tr> </tbody> </table>		Name	Execution Date	Kwan-soo Kim	12/03/2012	Tae-jong Lee	12/03/2012	Kang-sup Shin	12/03/2012	Si-bum Kim	12/03/2012	Yang-beom Kang	12/03/2012	Jong-yeul Jeong	12/03/2012
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<table border="1"> <tr> <td>Name:</td> <td>Magnachip Semiconductor, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk</td> </tr> <tr> <td>City:</td> <td>Cheongju-si</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	Magnachip Semiconductor, Ltd.	Street Address:	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk	City:	Cheongju-si	State/Country:	KOREA, REPUBLIC OF						
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13714866</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13714866										
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CORRESPONDENCE DATA															
Fax Number: 2023153758 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 202-429-0020 Email: info@nsiplaw.com Correspondent Name: NSIP LAW Address Line 1: P.O. Box 34688 Address Line 4: Washington, DISTRICT OF COLUMBIA 20043															
ATTORNEY DOCKET NUMBER:	023103.0068														
NAME OF SUBMITTER:	S. Laura Chung														
Total Attachments: 3 source=NewApp_0231030068_AssignmentExecuted#page1.tif source=NewApp_0231030068_AssignmentExecuted#page2.tif source=NewApp_0231030068_AssignmentExecuted#page3.tif															

OP \$40.00 13714866

ASSIGNMENT

For valuable consideration, we,

Kwan-soo KIM	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea
Tae-jong LEE	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea
Kang-sup SHIN	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea
Si-bum KIM	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea
Yang-beom KANG	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea
Jong-yeul JEONG	1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea

hereby assign to:

MAGNACHIP SEMICONDUCTOR, LTD., a Korean corporation having principal executive office(s) or place of business at: **1, Hyangjeong-dong, Hungduk-gu, Cheongju-si, Chungbuk, Republic of Korea**; and

its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Application Number 13/714,866 filed December 14, 2012 at the U.S. Patent & Trademark Office signed by us, with title **METAL WIRING OF SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME**, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and application serial number of said application when known; this Assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and

assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

IN TESTIMONY/WITNESS WHEREOF, we, undersigned inventors (Assignors) intending to be legally bound, have hereto affixed our signatures.

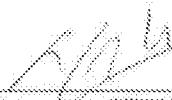
This 3rd day of December, 2012


Kwan-soo KIM

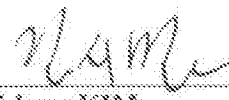
This 3rd day of Dec, 2012


Tae-jong LEE

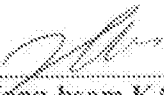
This 3rd day of Dec, 2012


Kang-sup SHIN

This 3rd day of Dec, 2012


Si-bum KIM

This 3rd day of Dec, 2012


Yang-beom KANG

This 7th day of Dec, 2012


Jong-yeul JEONG